

PAGE 1 OF 1

**APPLICATION FOR UNITED STATES PATENT  
DECLARATION AND POWER OF ATTORNEY**

As a below named inventor, I declare that my residence, post office address and citizenship are as stated below next to my name; that I verily believe that I am the original, first and sole inventor if only one name is listed below, or an original, first and joint inventor if plural inventors are named below, of the subject matter which is claimed and for which a patent is sought on the invention entitled as set forth below, which is described in the attached specification; that I have reviewed and understand the contents of the specification, including the claims, as amended by any amendment specifically referred to in the oath or declaration; that no application for patent or inventor's certificate on this invention has been filed by me or my legal representatives or assigns in any country foreign to the United States of America; and that I acknowledge my duty to disclose information which is material to the patentability of this application in accordance with Title 37, Code of Federal Regulations, Section 1.56;

I further declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true, and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

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| <b>TITLE OF INVENTION:</b><br><br><p style="text-align: center; font-size: 1.2em;">Waferlevel Method for Direct Bumping on Copper Pads in Integrated Circuits</p>                                       |  |   |
| <b>POWER OF ATTORNEY:</b> I HEREBY APPOINT PRACTITIONERS AT CUSTOMER NUMBER <b>23494</b> TO PROSECUTE THIS APPLICATION AND TRANSACT ALL BUSINESS IN THE PATENT AND TRADEMARK OFFICE CONNECTED THEREWITH |  |   |
| <b>SEND CORRESPONDENCE TO:</b><br><br>Gary C. Honeycutt<br>Texas Instruments Incorporated<br>P.O. Box 655474, MS 3999<br>Dallas, TX 75265   |  | <b>DIRECT TELEPHONE CALLS TO:</b><br><br>Gary C. Honeycutt<br>(214) 939-8651                      |
| <b>NAME OF INVENTOR:</b> (1)<br><br>Christo P. Bojkov   | <b>NAME OF INVENTOR:</b> (2)<br><br>Phillip Coffman  | <b>NAME OF INVENTOR:</b> (3)<br><br>Patricia B. Smith   |
| <b>RESIDENCE &amp; POST OFFICE ADDRESS:</b><br><br>8605 Kendall Drive<br>Plano, Texas 75025   | <b>RESIDENCE &amp; POST OFFICE ADDRESS:</b><br><br>6406 Nueces Bay Drive<br>Rowlett, Texas 75089 | <b>RESIDENCE &amp; POST OFFICE ADDRESS:</b><br><br>6902 Glenview Lane<br>Colleyville, Texas 76034 |
| <b>COUNTRY OF CITIZENSHIP:</b><br><br>United States   | <b>COUNTRY OF CITIZENSHIP:</b><br><br>United States  | <b>COUNTRY OF CITIZENSHIP:</b><br><br>  |
| <b>SIGNATURE OF INVENTOR:</b><br><br>   | <b>SIGNATURE OF INVENTOR:</b><br><br>  | <b>SIGNATURE OF INVENTOR:</b><br><br>   |
| <b>DATE:</b><br><br>  | <b>DATE:</b><br><br>   | <b>DATE:</b><br><br>  |

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I further declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true, and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

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| Waferlevel Method for Direct Bumping on Copper Pads in Integrated Circuits   |  |   |
| <b>POWER OF ATTORNEY:</b> I HEREBY APPOINT PRACTITIONERS AT CUSTOMER NUMBER 23494 TO PROSECUTE THIS APPLICATION AND TRANSACT ALL BUSINESS IN THE PATENT AND TRADEMARK OFFICE CONNECTED THEREWITH |  |   |
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| <b>COUNTRY OF CITIZENSHIP:</b><br>United States  | <b>COUNTRY OF CITIZENSHIP:</b><br>United States  | <b>COUNTRY OF CITIZENSHIP:</b><br>United States   |
| <b>SIGNATURE OF INVENTOR:</b><br>* <i>Chr. Bojkov</i>  | <b>SIGNATURE OF INVENTOR:</b><br>* <i>Phillip R Coffman</i>                                  | <b>SIGNATURE OF INVENTOR:</b><br>* <i>Patricia B Smith</i>                                    |
| <b>DATE:</b><br>* 3/26/02  | <b>DATE:</b><br>* 03/26/02   | <b>DATE:</b><br>* 3/28/02   |